

# **STIFEL US ROADSHOW**

Con

in

08 November 2021

# **AT&S AT A GLANCE**

# € 250 mn

EBITDA in FY 20/21 Margin of 20.7%



€ 1.2 bn

Revenue in FY 20/21

Employees

Vienna Listing Prime Standard

€ 1.3 bn

Market Cap as of end Q2 21/22 € 0.39 Dividend per share



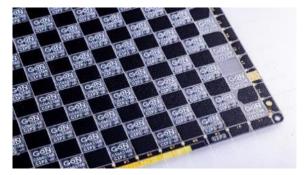
### AT&S SOLUTIONS ENABLE THE MOST ADVANCED ELECTRONICS APPLICATIONS AND TECHNOLOGIES







**HIGH-END PCBS** 







### **SEGMENT AUTOMOTIVE - INDUSTRIAL - MEDICAL**



- ADAS
- Autonomous driving (radar, camera, V-to-X communication)
- Power supply for motor systems



- Smart building, grid, lighting, manufacturing, transportation & retail
- Telecom infrastructure
- Power management
- Robots



- Diagnostics and imaging systems
- Therapy application (pacemakers, hearing aids, drug delivery ...)
- Patient monitoring

# Revenue share\* 26%

### EBITDA margin\* 7.4%

### Employees\*\* 2,956

\* in FY 20/21

\*\* as of end Q2 21/22; incl. leased personnel, average



### **SEGMENT MOBILE DEVICES & SUBSTRATES**



**Mobile devices** 

- Smartphones
- Wearables
- Notebooks & tablets
- Consumer electronics (action cameras and drones)



#### **IC** substrates

- High-performance computers
- Servers
- Client PCs
- Cloud & Edge computing
- 5G base stations
- Networking & gaming

# Revenue share\* **74%**

### EBITDA margin\* 22.4%

### Employees\*\* 9,334

\* in FY 20/21

\*\* as of end Q2 21/22; incl. leased personnel, average



### PROJECT UPDATE – CHONGQING III (CN)

- High volume manufacturing already started
- Ramp-up of capacities fully on track
- Full capacities available as of the beginning of Q3 23/24



### PROJECT UPDATE – CAMPUS KULIM (MY)

- Groundbreaking done
- Construction/piling started November 1<sup>st</sup>
- High volume production scheduled for the end of CY 2024

Stifel US Roadshow

AT&S



# € 500 MN INVESTMENT IN AUSTRIA AT&S SETS A NEW BENCHMARK IN EUROPE

#### Main Investments Leoben-Hinterberg 2020-2025

2020 – 2023

- Technology upgrade
- Substrate cores

2021 – 2022

New office building

Space for 300 employees

#### 2021 – 2025

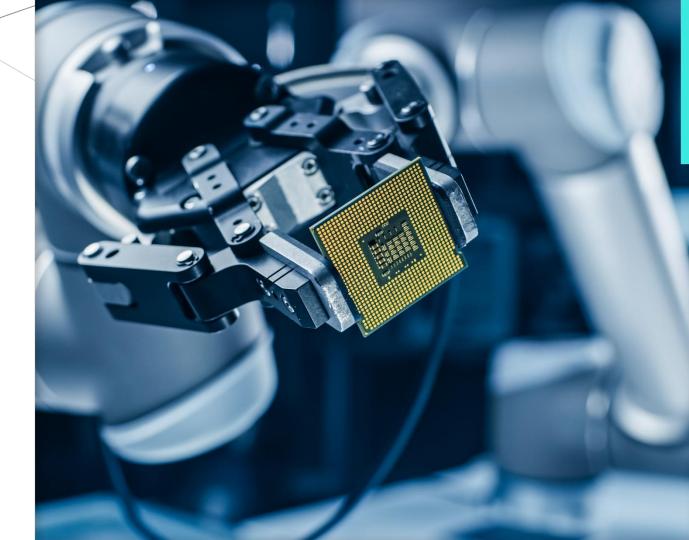
- R&D center for substrates
- Capacity for upscaling







### **RESULTS H1 21/22**





# **KEY DEVELOPMENTS H1 21/22**

Business expansion on track

- Strong revenue growth of +30%
  - All business segments contributed to company growth
  - Significant negative FX effects
- Headwind from increased material, transports and energy costs
- Strengthen the R&D activities to secure technology leadership
- Capacity expansion projects fully on track
- So far no significant impact from chip shortage
- Full-year and midterm revenue guidance increased

### H1 21/22 RESULTS SUMMARY

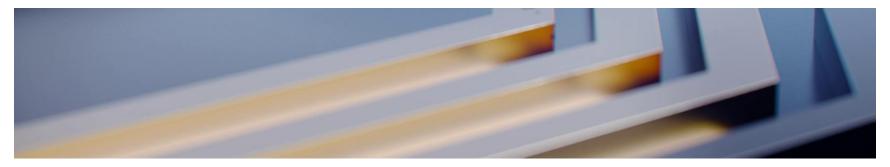
Revenue **+30%** € 698 mn

Negative FX effects of € 27 mn

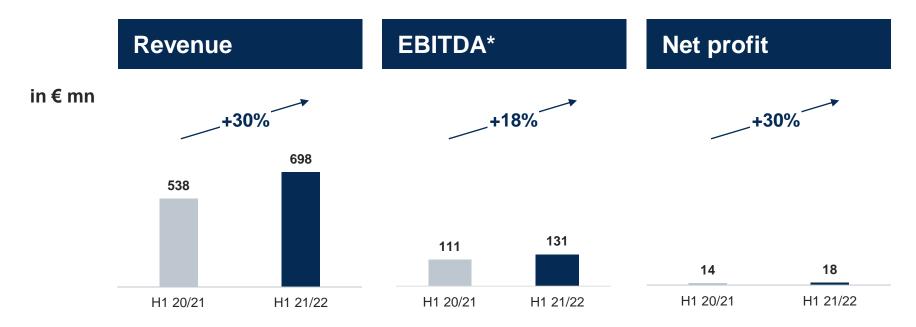
EBITDA margin -190 bps 18.8%

 EBITDA margin burdened by negative FX effects of € 29 mn Adjusted EBITDA margin -100 bps 20.1%

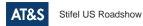
 Start-up costs for materials and wages of € 9.4 mn excluded



### H1 21/22 RESULTS SUMMARY



\* Adjusted EBITDA increase of 23% to € 140 mn (H1 2020/21: € 114 mn)



### OUTLOOK





# **CURRENT YEAR GUIDANCE**

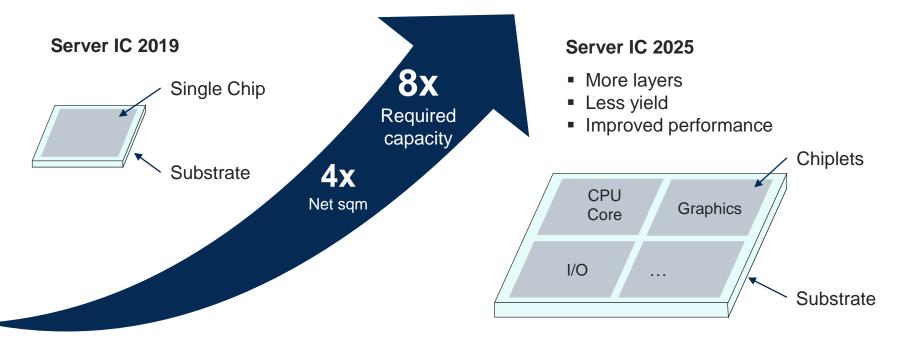
Growth	Revenue growth of 21 – 23% (previous: 17 – 19%)
Profitability	<ul> <li>Adjusted EBITDA margin of 21 – 23%</li> <li>Adjustment: Start-up effects of the Chongqing and Kulim projects with an amount of approx. € 50 mn</li> </ul>
•	

**Investments** Net capex of up to  $\in$  700 mn



# **IMPACT OF CHIPLETS ON ABF SUBSTRATE CAPACITY**

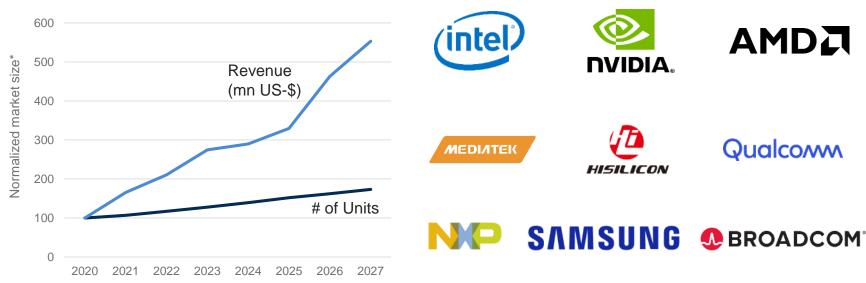
More capacity is needed due to larger form factor and increasing layer count of ABF substrates



&S Stifel US Roadshow

# **GLOBAL MARKET LEADERS USING ABF SUBSTRATES**

Significant growth rates due to increasing demand for ABF substrates



ABF Substrate Server\*\* market

\* Normalized to 2020 value \*\* Server CPUs, Accelerators, Networking Source: IDC, Prismark, internal assessment

# **MIDTERM GUIDANCE**

### FY 25/26 – Benefitting from projects in China and Malaysia

Growth	Revenue approx. € 3.5 bn (CAGR +24%) (previous: approx. € 3 bn)				
Profitability	<ul> <li>EBITDA margin of 27 – 32%</li> <li>ROCE of &gt;12% with ramp-up of production</li> </ul>				
Others	<ul> <li>Net debt/EBITDA: &lt;3 (can be temporarily exceeded)</li> <li>Equity ratio: &gt;30% (may temporarily fall below)</li> </ul>				



# **GOOD REASONS FOR INVESTING IN AT&S**

#### Unique market position

- Broad product portfolio to serve all growth markets
- Long-standing customer relationships with technology and market leaders
- Technology innovator due to continuous R&D efforts
- Quality benchmark with outstanding process know-how, productivity and efficiency

#### Growth oriented strategy

- Megatrend-driven markets with attractive growth potential
- Address growth opportunities with incremental investments
- Constant outperformance of the PCB & substrates market



# THANK YOU FOR YOUR ATTENTION



# **HIGH-END FOCUS RESULTS IN STRONGER GROWTH**

### AUTOMOTIVE

- Dynamic recovery
- Chip shortage effects limited



### INDUSTRIAL

- Infrastructure investments
- Economy tailwind



#### **MEDICAL**

- Stable growth rates
- Diversification of applications



10%

22%

19%

YoY Market Growth

# **POSITIVE MOMENTUM IN OUR MAIN MARKETS**

### CONSUMER – COMPUTER – COMMUNICATION

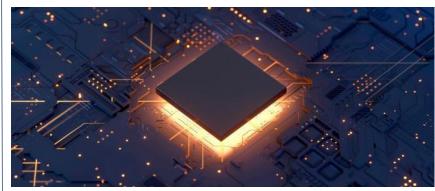
- Growth driver work/stay/play at home
- Diversification on track



18% | 18% | 13.5%

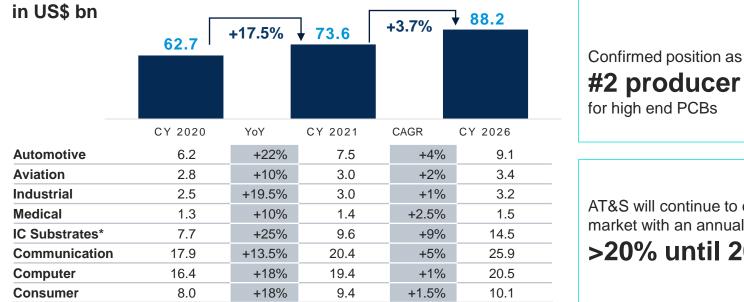
### SUBSTRATES / SEMICON

- Dynamic market growth limited by capacity
- Partnering with customers to expand



YoY Market Growth

# **AT&S OUTPERFORMS PCB & SUBSTRATES MARKET** GROWTH



AT&S will continue to outperform the market with an annual growth of >20% until 2026

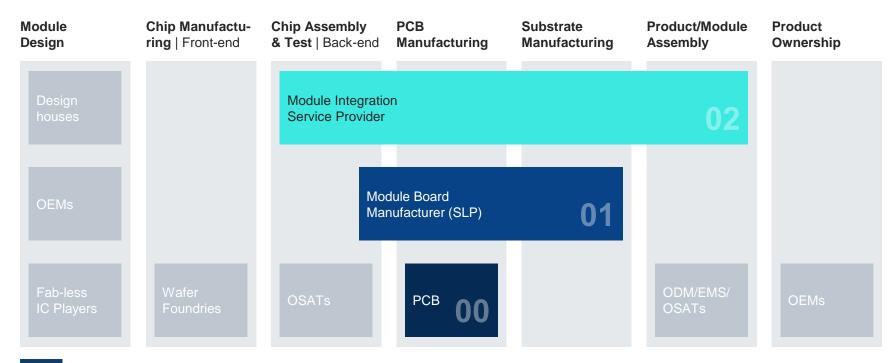
> Source: Prismark 05-09/2021 \* only containing high-end IC substrates

## **MARKET PLAYERS IN THE HIGH-END SEGMENT**

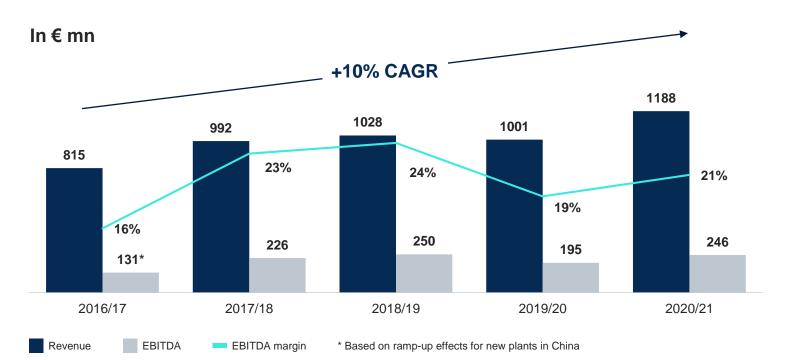
HDI Technology <sup>1</sup>		ABF Substrates <sup>2</sup>		
1	Compeq	1	Ibiden	
2	AT&S	2	Unimicron	
3	Unimicron	3	SEMCO	
4	Tripod	4	Shinko	
5	Zhen Ding	5	AT&S	
6	AKM Meadville	6	Kyocera	
7	Meiko	7	Nan Ya PCB	
8	ТТМ	8	Kinsus	



# **AT&S SOLUTIONS FOR THE ELECTRONICS INDUSTRY**



### **MULTI-YEAR OVERVIEW**









<b>Leoben, headquarters</b>	<b>Fehring</b>	<b>Nanjangud</b>	<b>Chongqing</b>	<b>Shanghai</b>	<b>Ansan</b>	<b>Kulim</b>
Austria	Austria	India	China	China	Korea	Malaysia
1,054*	389*	1,354*	3,741*	4,477*	255*	6,000 by 2024



AT&S plant

# **DRIVING SUSTAINABILITY**

High level of social, ecological and economic responsibility

### <u>2025</u>

<b>80%</b> renewable energies	<b>30%</b> share of women in leadership positions		
Vitality Index	Strengthening partnerships		
>20%	with suppliers		

#### **Achievements**<sup>\*</sup>



### Rated by





Corporate ESG Performance		
Performance	Prime	
ISS ESG	rnne	





\* As of 31.03.2021 | \*\* Including big hydro power



### **R&D – BASIS FOR TECHNOLOGY LEADERSHIP**

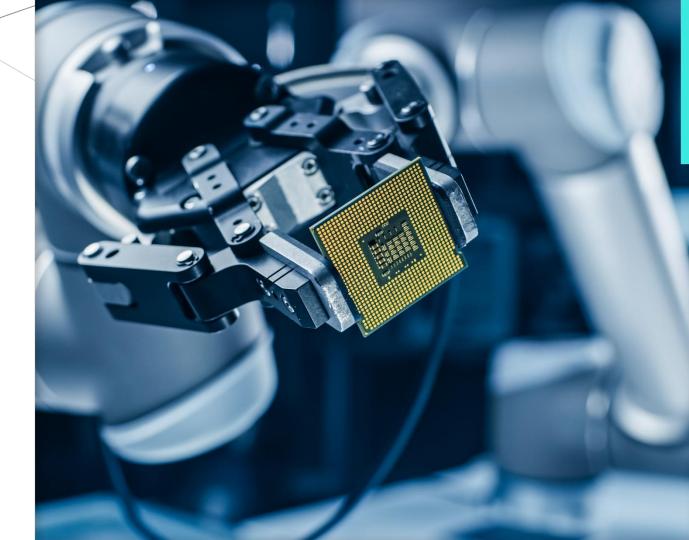


Status: FY 2020/21

\*Share of revenue of technologically innovative products made in the last three years (previously: Innovation Revenue Rate)



### **RESULTS H1 21/22**

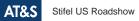




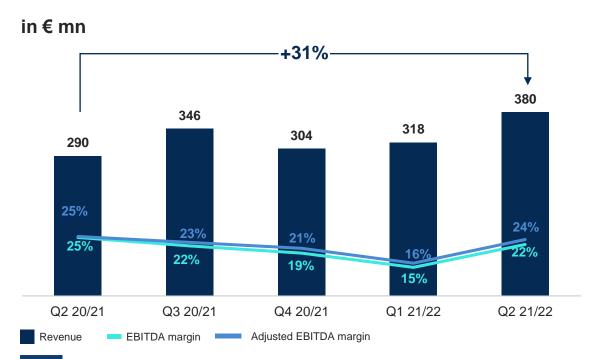
### **EBITDA BRIDGE H1**



Investments to prepare for future growth



### **QUARTERLY DEVELOPMENT**



Highest quarterly revenue in history

Higher R&D expenses to secure future growth

**Profitability** burdened by FX effects and higher material costs

# **BUSINESS DEVELOPMENT**

#### **Mobile Devices & Substrates**





Additional Chongqing capacity lifts revenue to record level

Growing demand for **PCBs for modules** 

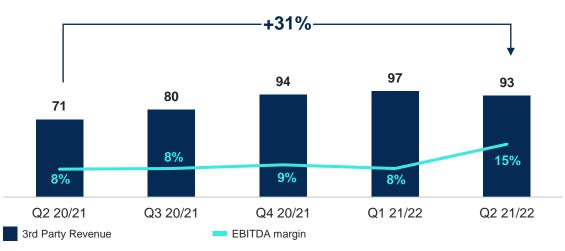
**EBITDA margin** neg. influenced by FX effects and start-up costs



# **BUSINESS DEVELOPMENT**

#### Automotive, Industrial & Medical

in € mn



All divisions grew YoY with Industrial as main driver

**No significant impact** from chip shortage

Margin includes EU IPCEI funding in **key technologies** 



# H1 21/22 FINANCIAL POSITION

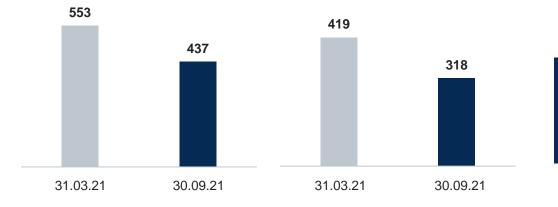
#### Cash & cash equivalents

in € mn



### **Balancing capital allocation**

 Deploying capital with clear approach to invest in strategic growth markets



Solid financial structure with € 755 mn cash, cash equivalents and unused credit lines

### **BALANCE SHEET**

€mn	31.03.2021	30.09.2021	Change in %	
Total assets	2,390	2,640	+10%	Ongoing expansion and technology upgrades main drivers for increase in total assets
Equity	802	872	+9%	
Equity ratio	34%	33%	-54bps	Stronger increase in total assets weighs on equity ratio
Net debt	509	787	+55%	Higher CAPEX feeds into liquidity and drives up net debt



### **CASH FLOW**

€mn	H1 20/21	H1 21/22	YoY Change in %	
CF from operating activities	84	78	-7%	
CF from investing activities	-238	-283	-19%	Higher CAPEX offset by lower investments in time deposits
CF from financing activities	102	88	-14%	
Operating free CF*	-112	-229	>-100%	Operating free CF mainly driven by higher CAPEX
Net capex	196	307	+57%	

\* Cash flow from operating activities minus Net capex



### DISCLAIMER

This presentation is provided by AT & S Austria Technologie & Systemtechnik Aktiengesellschaft, having its headquarter at Fabriksgasse 13, 8700 Leoben, Austria ("AT&S"), and the contents are proprietary to AT&S and for information only.

AT&S does not provide any representations or warranties with regard to this presentation or for the correctness and completeness of the statements contained therein, and no reliance may be placed for any purpose whatsoever on the information contained in this presentation, which has not been independently verified. You are expressly cautioned not to place undue reliance on this information.

This presentation may contain forward-looking statements which were made on the basis of the information available at the time of preparation and on management's expectations and assumptions. However, such statements are by their very nature subject to known and unknown risks and uncertainties. As a result, actual developments, results, performance or events may vary significantly from the statements contained explicitly or implicitly herein.

Neither AT&S, nor any affiliated company, or any of their directors, officers, employees, advisors or agents accept any responsibility or liability (for negligence or otherwise) for any loss whatsoever out of the use of or otherwise in connection with this presentation. AT&S undertakes no obligation to update or revise any forward-looking statements, whether as a result of changed assumptions or expectations, new information or future events.

This presentation does not constitute a recommendation, an offer or invitation, or solicitation of an offer, to subscribe for or purchase any securities, and neither this presentation nor anything contained herein shall form the basis of any contract or commitment whatsoever. This presentation does not constitute any financial analysis or financial research and may not be construed to be or form part of a prospectus. This presentation is not directed at, or intended for distribution to or use by, any person or entity that is a citizen or resident or located in any locality, state, country or other jurisdiction where such distribution, publication, availability or use would be contrary to law or regulation or which would require any registration or licensing within such jurisdiction.

